

Title (en)

DIAMOND CONDITIONING OF SOFT CHEMICAL MECHANICAL PLANARIZATION/POLISHING (CMP) POLISHING PADS

Title (de)

DIAMANTABRICHTUNG VON WEICHEN CMP-POLIERKISSEN (CMP - CHEMISCH-MECHANISCHES PLANARISIEREN/POLIEREN)

Title (fr)

CONDITIONNEMENT AU DIAMANT DE TAMPONS DE POLISSAGE/PLANARISATION MECANO-CHIMIQUE (CMP)

Publication

**EP 1641596 A1 20060405 (EN)**

Application

**EP 03816708 A 20031215**

Priority

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- US 40257803 A 20030328

Abstract (en)

[origin: US2004192178A1] Conditioning of chemical mechanical planarization (CMP) using conventional diamond-embedded abrasive strips are well suited to condition conventional "hard" polishing but not soft polishing pads because the diamonds not only remove waste material, but they also damage the polishing surface of the pad. Embodiments of the present invention condition soft polishing pads using diamond strips without damaging the soft polishing pad.

IPC 1-7

**B24B 37/04**; **B24B 53/007**

IPC 8 full level

**B24B 53/007** (2006.01); **B24B 53/017** (2012.01)

CPC (source: EP KR US)

**B24B 37/04** (2013.01 - KR); **B24B 53/007** (2013.01 - KR); **B24B 53/017** (2013.01 - EP KR US)

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